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Dual 12-/14-/16-Bit, LVDS Interface, 500 MSPS DACs

Data Sheet

AD9780/AD9781/AD9783

FEATURES

High dynamic range, dual DAC parts
Low noise and intermodulation distortion
Single carrier W-CDMA ACLR = 80 dBc @ 61.44 MHz IF
Innovative switching output stage permits usable outputs
beyond Nyquist frequency

LVDS inputs with dual-port or optional interleaved singleport operation

Differential analog current outputs are programmable from 8.6 mA to 31.7 mA full scale

Auxiliary 10-bit current DACs with source/sink capability for external offset nulling

Internal 1.2 V precision reference voltage source Operates from 1.8 V and 3.3 V supplies 315 mW power dissipation Small footprint, RoHS compliant, 72-lead LFCSP

APPLICATIONS

Wireless infrastructure
W-CDMA, CDMA2000, TD-SCDMA, WiMAX
Wideband communications
LMDS/MMDS, point-to-point
RF signal generators, arbitrary waveform generators

GENERAL DESCRIPTION

The AD9780/AD9781/AD9783 include pin-compatible, high dynamic range, dual digital-to-analog converters (DACs) with 12-/14-/16-bit resolutions, and sample rates of up to 500 MSPS. The devices include specific features for direct conversion transmit applications, including gain and offset compensation, and they interface seamlessly with analog quadrature modulators such as the ADL5370.

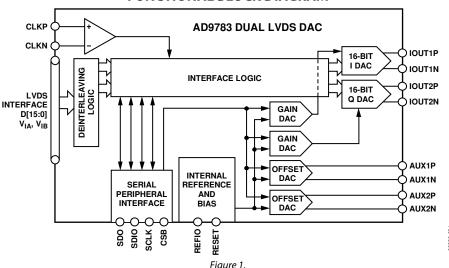
A proprietary, dynamic output architecture permits synthesis of analog outputs even above Nyquist by shifting energy away from the fundamental and into the image frequency.

Full programmability is provided through a serial peripheral interface (SPI) port. Some pin-programmable features are also offered for those applications without a controller.

PRODUCT HIGHLIGHTS

- 1. Low noise and intermodulation distortion (IMD) enable high quality synthesis of wideband signals.
- 2. Proprietary switching output for enhanced dynamic performance.
- 3. Programmable current outputs and dual auxiliary DACs provide flexibility and system enhancements.

FUNCTIONAL BLOCK DIAGRAM



Data Sheet

AD9780/AD9781/AD9783

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11/07—Revision 0: Initial Version

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SPECIFICATIONS

DC SPECIFICATIONS

 T_{MIN} to T_{MAX} , AVDD33 = 3.3 V, DVDD33 = 3.3 V, DVDD18 = 1.8 V, CVDD18 = 1.8 V, I_{OUTFS} = 20 mA maximum sample rate, unless otherwise noted.

Table 1.

	AD9780 AD9781		1	AD9783						
Parameter	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
RESOLUTION		12			14			16		Bits
ACCURACY										
Differential Nonlinearity (DNL)		±0.13			±0.5			±2		LSB
Integral Nonlinearity (INL)		±0.25			±1			±4		LSB
MAIN DAC OUTPUTS										
Offset Error	-0.001	0	+0.001	-0.001	0	+0.001	-0.001	0	+0.001	% FSR
Gain Error (with Internal Reference)		±2			±2			±2		% FSR
Full-Scale Output Current ¹	8.66	20.2	31.66	8.66	20.2	31.66	8.66	20.2	31.66	mA
Output Compliance Range	-1.0		+1.0	-1.0		+1.0	-1.0		+1.0	V
Output Resistance		10			10			10		ΜΩ
Main DAC Monotonicity Guaranteed										
MAIN DAC TEMPERATURE DRIFT										
Offset		0.04			0.04			0.04		ppm/°C
Gain		100			100			100		ppm/°C
Reference Voltage		30			30			30		ppm/°C
AUX DAC OUTPUTS										
Resolution		10			10			10		Bits
Full-Scale Output Current	-2		+2	-2		+2	-2		+2	mA
Output Compliance Range (Source)	0		1.6	0		1.6	0		1.6	V
Output Compliance Range (Sink)	0.8		1.6	0.8		1.6	0.8		1.6	V
Output Resistance		1			1			1		ΜΩ
AUX DAC Monotonicity Guaranteed										
REFERENCE										
Internal Reference Voltage		1.2			1.2			1.2		V
Output Resistance		5			5			5		kΩ
ANALOG SUPPLY VOLTAGES										
AVDD33	3.13	3.3	3.47	3.13	3.3	3.47	3.13	3.3	3.47	V
CVDD18	1.70	1.8	1.90	1.70	1.8	1.90	1.70	1.8	1.90	V
DIGITAL SUPPLY VOLTAGES										
DVDD33	3.13	3.3	3.47	3.13	3.3	3.47	3.13	3.3	3.47	V
DVDD18	1.70	1.8	1.90	1.70	1.8	1.90	1.70	1.8	1.90	V
POWER CONSUMPTION										
$f_{DAC} = 500 \text{ MSPS}, IF = 20 \text{ MHz}$		$V \times I$	$V \times I$		$V \times I$	$V \times I$		$V \times I$	$V \times I$	mW
$f_{DAC} = 500 \text{ MSPS, IF} = 10 \text{ MHz}$		440			440			440		mW
Power-Down Mode		3	5		3	5		3	35	mW
SUPPLY CURRENTS ²										
AVDD33		55	58		55	58		55	58	mA
CVDD18		34	38		34	38		34	38	mA
DVDD33		13	15		13	15		13	15	mA
DVDD18		68	85		68	85		68	85	mA

 $^{^{\}scriptscriptstyle 1}$ Based on a 10 $k\Omega$ external resistor.

 $^{^2}$ f_{DAC} = 500 MSPS, f_{OUT} = 20 MHz.

DIGITAL SPECIFICATIONS

 T_{MIN} to T_{MAX} , AVDD33 = 3.3 V, DVDD33 = 3.3 V, DVDD18 = 1.8 V, CVDD18 = 1.8 V, I_{OUTFS} = 20 mA maximum sample rate, unless otherwise noted.

Table 2.

Parameter	Min	Тур	Max	Unit
DAC CLOCK INPUT (CLKP, CLKN)				
Differential Peak-to-Peak Voltage (CLKP – CLKN)	400	800	1600	mV
Common-Mode Voltage	300	400	500	mV
Maximum Clock Rate	500			MSPS
DAC CLOCK TO ANALOG OUTPUT DATA LATENCY			7	Cycles
SERIAL PERIPHERAL INTERFACE (CMOS INTERFACE)				
Maximum Clock Rate (SCLK)			40	MHz
Minimum Pulse Width High			12.5	ns
Minimum Pulse Width Low			12.5	ns
Setup time, SDI to SCLK (t _{DS})	2.0			ns
Hold Time , SDI to to SCLK (t _{DH})	0.2			ns
Data Valid ,SDO to SCLK, (t _{DV})	2.3			ns
Setup time, CSB to SCLK (t _{DCSB})		1.4		ns
SERIAL PERIPHERAL INTERFACE LOGIC LEVELS				
Input Logic High	2.0			V
Input Logic Low			0.8	V
DIGITAL INPUT DATA (LVDS INTERFACE)				
Input Voltage Range, VIA or VIB	800		1600	mV
Input Differential Threshold, VIDTH	-100		+100	mV
Input Differential Hysteresis, VIDTHH to VIDTHL		20		mV
Input Differential Input Impedance, R _{IN}	80		120	Ω
Maximum LVDS Input Rate (per DAC)	500			MSPS

AC SPECIFICATIONS

 T_{MIN} to T_{MAX} , AVDD33 = 3.3 V, DVDD33 = 3.3 V, DVDD18 = 1.8 V, CVDD18 = 1.8 V, I_{OUTFS} = 20 mA, maximum sample rate, unless otherwise noted.

Table 3.

	AD9780			AD9781			AD9783			· · · · · · · · · · · · · · · · · · ·
Parameter	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
SPURIOUS FREE DYNAMIC RANGE (SFDR)										
$f_{DAC} = 500 \text{ MSPS}, f_{OUT} = 20 \text{ MHz}$		79			78			80		dBc
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 120 \text{ MHz}$		67			66			68		dBc
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 380 \text{ MHz}$ (Mix Mode)		55			58			62		dBc
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 480 \text{ MHz}$ (Mix Mode)		58			62			59		dBc
TWO-TONE INTERMODULATION DISTORTION (IMD)										
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 20 \text{ MHz}$		91			93			86		dBc
$f_{DAC} = 500 \text{ MSPS}, f_{OUT} = 120 \text{ MHz}$		80			75			79		dBc
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 380 \text{ MHz}$ (Mix Mode)		69			70			64		dBc
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 480 \text{ MHz}$ (Mix Mode)		60.5			61.5			66		dBc
ONE-TONE NOISE SPECTRAL DENSITY (NSD)										
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 40 \text{ MHz}$		-157			-162			-165		dBc
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 120 \text{ MHz}$		-154.5			-156.5			-157		dBc
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 380 \text{ MHz}$ (Mix Mode)		-153			-153			-154		dBc
$f_{DAC} = 500 \text{ MSPS}$, $f_{OUT} = 480 \text{ MHz}$ (Mix Mode)		-152			-152			-153		dBc
W-CDMA ADJACENT CHANNEL LEAKAGE RATIO (ACLR), SINGLE CARRIER										
$f_{DAC} = 491.52 \text{ MSPS}, f_{OUT} = 20 \text{ MHz}$		-81			-82.5			-82		dBc
$f_{DAC} = 491.52 \text{ MSPS}, f_{OUT} = 80 \text{ MHz}$		-80			-82.5			-81		dBc
$f_{DAC} = 491.52 \text{ MSPS}, f_{OUT} = 411.52 \text{ MHz}$		-71			-68			-69		dBc
$f_{DAC} = 491.52 \text{ MSPS}, f_{OUT} = 471.52 \text{ MHz}$		-69			-69			-70		dBc

ABSOLUTE MAXIMUM RATINGS

Table 4.

	With	
Parameter	Respect to	Rating
AVDD33, DVDD33	AGND, DGND, CGND	-0.3 V to +3.6 V
DVDD18, CVDD18	AGND, DGND, CGND	-0.3 V to +1.98 V
AGND	DGND, CGND	-0.3 V to +0.3 V
DGND	AGND, CGND	-0.3 V to +0.3 V
CGND	AGND, DGND	-0.3 V to +0.3 V
REFIO	AGND	-0.3 V to AVDD33 + 0.3 V
IOUT1P, IOUT1N, IOUT2P, IOUT2N, AUX1P, AUX1N, AUX2P, AUX2N	AGND	-1.0 V to AVDD33 + 0.3 V
D15 to D0	DGND	-0.3 V to DVDD33 + 0.3 V
CLKP, CLKN	CGND	-0.3 V to CVDD18 + 0.3 V
CSB, SCLK, SDIO, SDO	DGND	-0.3 V to DVDD33 + 0.3 V
Junction Temperature		+125°C
Storage Temperature		−65°C to +150°C

THERMAL RESISTANCE

Thermal resistance is tested using a JEDEC standard 4-layer thermal test board with no airflow.

Table 5.

Package Type	Θ_{JA}	Unit
CP-72-1 (Exposed Pad Soldered to PCB)	25	°C/W

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

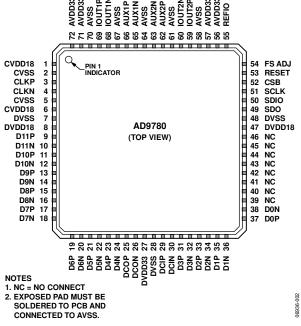


Figure 2. AD9780 Pin Configuration

Table 6. AD9780 Pin Function Descriptions

Pin No.	Mnemonic	Description			
1, 6	CVDD18	Clock Supply Voltage (1.8 V).			
2, 5	CVSS	Clock Supply Return.			
3, 4	CLKP, CLKN	Differential DAC Sampling Clock Input.			
7, 28, 48	DVSS	Digital Common.			
8, 47	DVDD18	Digital Supply Voltage (1.8 V).			
9 to 24, 31 to 38	D11P, D11N to D0P, D0N	LVDS Data Inputs. D11 is the MSB, D0 is the LSB.			
25, 26	DCOP, DCON	Differential Data Clock Output. Clock at the DAC sample rate.			
27	DVDD33	Digital Input and Output Pad Ring Supply Voltage (3.3 V).			
29, 30	DCIP, DCIN	Differential Data Clock Input. Clock aligned with input data.			
39 to 46	NC	No Connection. Leave these pins floating.			
49	SDO	Serial Port Data Output.			
50	SDIO	Serial Port Data Input (4-Wire Mode) or Bidirectional Serial Data Line (3-Wire Mode).			
51	SCLK	Serial Port Clock Input.			
52	CSB	Serial Port Chip Select (Active Low).			
53	RESET	Chip Reset (Active High).			
54	FS ADJ	Full-Scale Current Output Adjust.			
55	REFIO	Analog Reference Input/Output (1.2 V Nominal).			
56, 57, 71, 72	AVDD33	Analog Supply Voltage (3.3 V).			
58, 61, 64, 67, 70	AVSS	Analog Common.			
59	IOUT2P	DAC Current Output. Full-scale current is sourced when all data bits are 1s.			
60	IOUT2N	Complementary DAC Current Output. Full-scale current is sourced when all data bits are 0s			
62, 63	AUX2P, AUX2N	Differential Auxiliary DAC Current Output (Channel 2).			
65, 66	AUX1N, AUX1P	Differential Auxiliary DAC Current Output (Channel 1).			
68	IOUT1N	Complementary DAC Current Output. Full-scale current is sourced when all data bits are 0s			
69	IOUT1P	DAC Current Output. Full-scale current is sourced when all data bits are 1s.			
Heat Sink Pad	N/A	The heat sink pad on the bottom of the package should be soldered to the PCB plane that carries AVSS.			

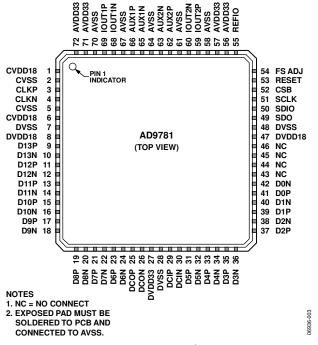


Figure 3. AD9781 Pin Configuration

Table 7. AD9781 Pin Function Descriptions

Pin No.	Mnemonic	Description
1, 6	CVDD18	Clock Supply Voltage (1.8 V).
2, 5	CVSS	Clock Supply Return.
3, 4	CLKP, CLKN	Differential DAC Sampling Clock Input.
7, 28, 48	DVSS	Digital Common.
8, 47	DVDD18	Digital Supply Voltage (1.8 V).
9 to 24, 31 to 42	D13P, D13N to D0P, D0N	Data Inputs. D13 is the MSB, D0 is the LSB.
25, 26	DCOP, DCON	Differential Data Clock Output. Clock at the DAC sample rate.
27	DVDD33	Digital Input and Output Pad Ring Supply Voltage (3.3 V).
29, 30	DCIP, DCIN	Differential Data Clock Input. Clock aligned with input data.
43 to 46	NC	No Connection. Leave these pins floating.
49	SDO	Serial Port Data Output.
50	SDIO	Serial Port Data Input (4-Wire Mode) or Bidirectional Serial Data Line (3-Wire Mode).
51	SCLK	Serial Port Clock Input.
52	CSB	Serial Port Chip Select (Active Low).
53	RESET	Chip Reset (Active High).
54	FS ADJ	Full-Scale Current Output Adjust.
55	REFIO	Analog Reference Input/Output (1.2 V Nominal).
56, 57, 71, 72	AVDD33	Analog Supply Voltage (3.3 V).
58, 61, 64, 67, 70	AVSS	Analog Common.
59	IOUT2P	DAC Current Output. Full-scale current is sourced when all data bits are 1s.
60	IOUT2N	Complementary DAC Current Output. Full-scale current is sourced when all data bits are 0s.
62, 63	AUX2P, AUX2N	Differential Auxiliary DAC Current Output (Channel 2).
65, 66	AUX1N, AUX1P	Differential Auxiliary DAC Current Output (Channel 1).
68	IOUT1N	Complementary DAC Current Output. Full-scale current is sourced when all data bits are 0s.
69	IOUT1P	DAC Current Output. Full-scale current is sourced when all data bits are 1s.
Heat Sink Pad	N/A	The heat sink pad on the bottom of the package should be soldered to the PCB plane that carries AVSS.

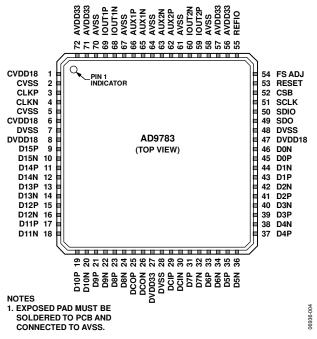


Figure 4. AD9783 Pin Configuration

Table 8. AD9783 Pin Function Descriptions

Pin No.	Mnemonic	Description			
1, 6	CVDD18	Clock Supply Voltage (1.8 V).			
2, 5	CVSS	Clock Supply Return.			
3, 4	CLKP, CLKN	Differential DAC Sampling Clock Input.			
7, 28, 48	DVSS	Digital Common.			
8, 47	DVDD18	Digital Supply Voltage (1.8 V).			
9 to 24, 31 to 46	D15P, D15N to D0P, D0N	LVDS Data Inputs. D15 is the MSB, D0 is the LSB.			
25, 26	DCOP, DCON	Differential Data Clock Output. Clock at the DAC sample rate.			
27	DVDD33	Digital Input and Output Pad Ring Supply Voltage (3.3 V).			
29, 30	DCIP, DCIN	Differential Data Clock Input Clock aligned with input data.			
49	SDO	Serial Port Data Output.			
50	SDIO	Serial Port Data Input (4-Wire Mode) or Bidirectional Serial Data Line (3-Wire Mode).			
51	SCLK	Serial Port Clock Input.			
52	CSB	Serial Port Chip Select (Active Low).			
53	RESET	Chip Reset (Active High).			
54	FS ADJ	Full-Scale Current Output Adjust.			
55	REFIO	Analog Reference Input/Output (1.2 V Nominal).			
56, 57, 71, 72	AVDD33	Analog Supply Voltage (3.3 V).			
58, 61, 64, 67, 70	AVSS	Analog Common.			
59	IOUT2P	DAC Current Output. Full-scale current is sourced when all data bits are 1s.			
60	IOUT2N	Complementary DAC Current Output. Full-scale current is sourced when all data bits are 0s.			
62, 63	AUX2P, AUX2N	Differential Auxiliary DAC Current Output (Channel 2).			
65, 66	AUX1N, AUX1P	Differential Auxiliary DAC Current Output (Channel 1).			
68	IOUT1N	Complementary DAC Current Output. Full-scale current is sourced when all data bits are 0s.			
69	IOUT1P	DAC Current Output. Full-scale current is sourced when all data bits are 1s.			
Heat Sink Pad	N/A	The heat sink pad on the bottom of the package should be soldered to the PCB plane that carries AVSS.			

TYPICAL PERFORMANCE CHARACTERISTICS

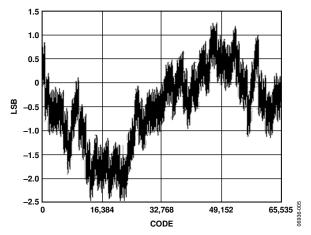


Figure 5. AD9783 INL, $T_A = 85$ °C, FS = 20 mA

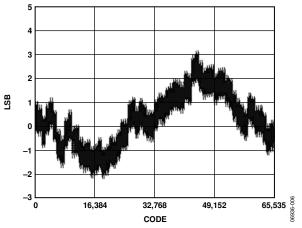


Figure 6. AD9783 INL, $T_A = 25$ °C, FS = 20 mA

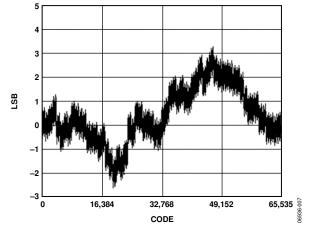


Figure 7. AD9783 INL, $T_A = -40$ °C, FS = 20 mA

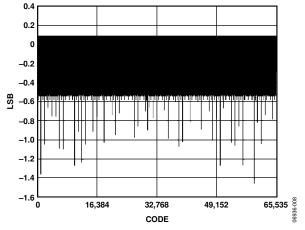


Figure 8. AD9783 DNL, $T_A = 85$ °C, FS = 20 mA

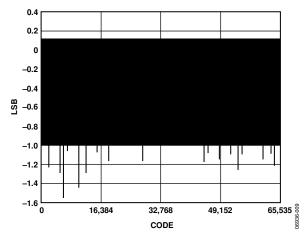


Figure 9. AD9783 DNL, $T_A = 25$ °C, FS = 20 mA

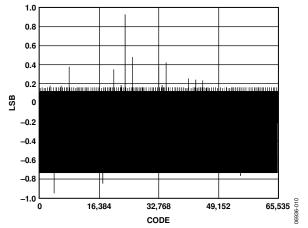


Figure 10. AD9783 DNL, $T_A = -40$ °C, FS = 20 mA

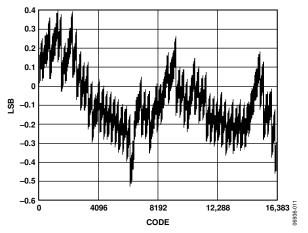


Figure 11. AD9781 INL, $T_A = 85$ °C, FS = 20 mA

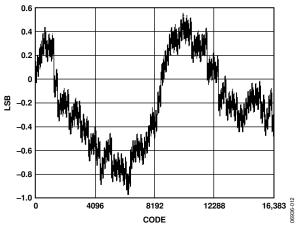


Figure 12. AD9781 INL, $T_A = -40^{\circ}\text{C}$, FS = 20 mA

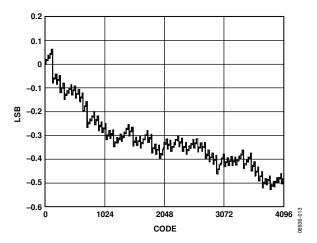


Figure 13. AD9780 INL, $T_A = -40$ °C, FS = 20 mA

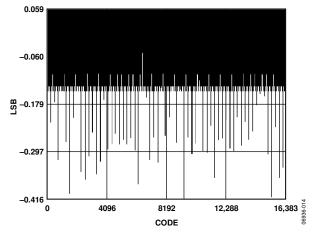


Figure 14. AD9781 DNL, $T_A = 85$ °C, FS = 20 mA

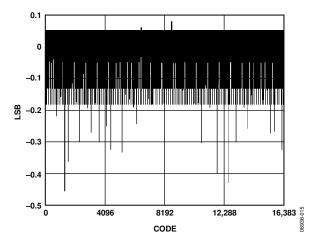


Figure 15. AD9781 DNL, $T_A = -40$ °C, FS = 20 mA

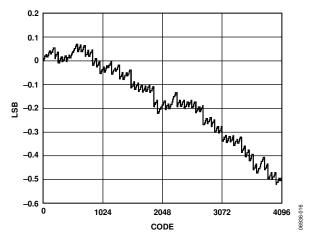


Figure 16. AD9780 INL, $T_A = 85$ °C, FS = 20 mA

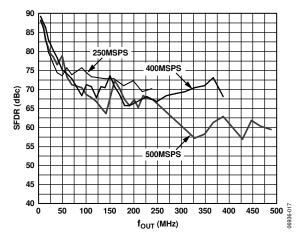


Figure 17. AD9783 SFDR vs. f_{OUT} Over f_{DAC} in Baseband and Mix Modes, FS = 20 mA

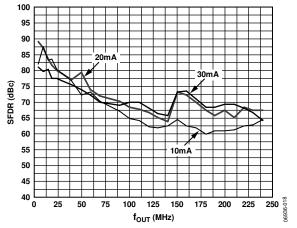


Figure 18. AD9783 SFDR vs. f_{OUT} Over Analog Output, $T_A = 25$ °C, at 500 MSPS

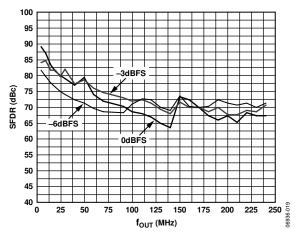


Figure 19. AD9783 SFDR vs. f_{OUT} Over Digital Input Level, $T_A = 25$ °C, at 500 MSPS, FS = 20 mA

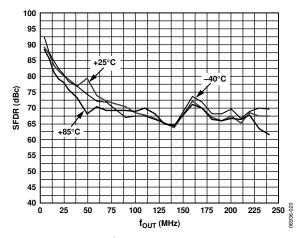


Figure 20. AD9783 SFDR vs. f_{OUT} Over Temperature, at 500 MSPS, FS = 20 mA

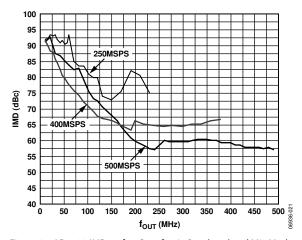


Figure 21. AD9783 IMD vs. f_{OUT} Over f_{DAC} in Baseband and Mix Modes, FS = 20 mA

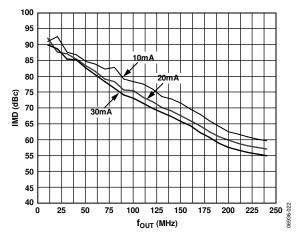


Figure 22. AD9783 IMD vs. f_{OUT} Over Analog Output, $T_A = 25$ °C, at 500 MSPS

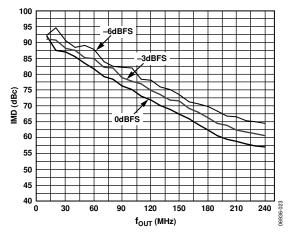


Figure 23. AD9783 IMD vs. f_{OUT} Over Digital Input Level, T_A = 25°C, at 500 MSPS, FS = 20 mA

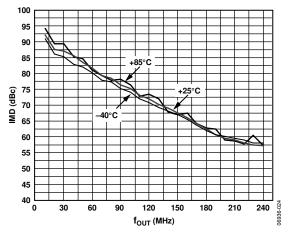


Figure 24. AD9783 IMD vs. f_{OUT} Over Temperature, at 500 MSPS, FS = 20 mA

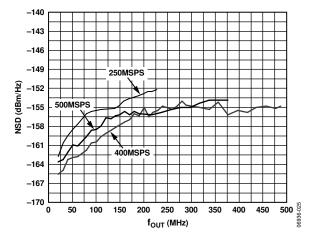


Figure 25. AD9783 One-Tone NSD vs. f_{OUT} Over f_{DAC} Baseband and Mix Modes, FS = 20 mA

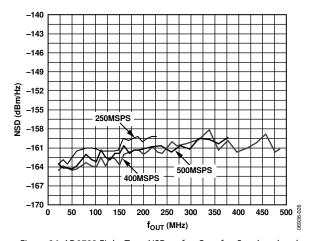


Figure 26. AD9783 Eight-Tone NSD vs. f_{OUT} Over f_{DAC} Baseband and Mix Modes, FS = 20 mA

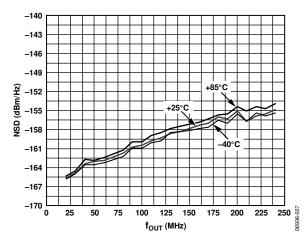


Figure 27. AD9783 One-Tone NSD vs. f_{OUT} Over Temperature, at 500 MSPS, FS = 20 mA

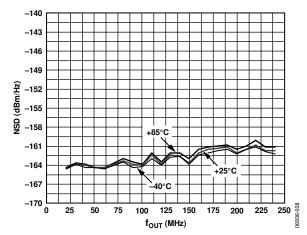


Figure 28. AD9783 Eight-Tone NSD vs. f_{OUT} Over Temperature, at 500 MSPS, FS = 20 mA

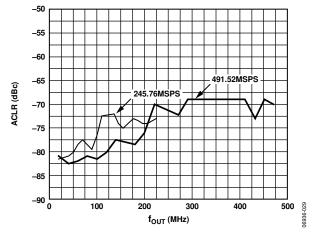


Figure 29. AD9783 ACLR for First Adjacent Band One-Carrier W-CDMA Baseband and Mix Modes, FS = 20 mA

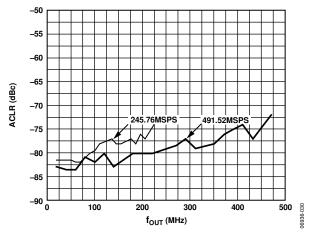


Figure 30. AD9783 ACLR for Second Adjacent Band One-Carrier W-CDMA Baseband and Mix Modes, FS = 20 mA

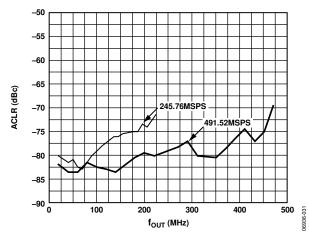


Figure 31. AD9783 ACLR for Third Adjacent Band One-Carrier W-CDMA Baseband and Mix Modes, FS = 20 mA

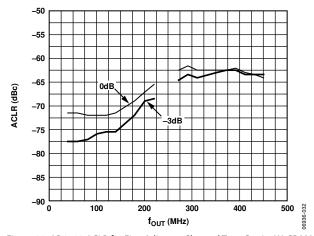


Figure 32. AD9783 ACLR for First Adjacent Channel Two-Carrier W-CDMA Over Digital Input Level Baseband and Mix Modes, at 491.52 MSPS, FS = 20 mA

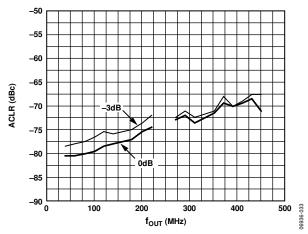


Figure 33. AD9783 ACLR for Second Adjacent Channel Two-Carrier W-CDMA Over Digital Input Level Baseband and Mix Modes, at 491.52 MSPS, FS = 20 mA

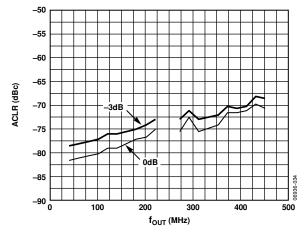


Figure 34. AD9783 ACLR for Third Adjacent Channel Two-Carrier W-CDMA Over Digital Input Level Baseband and Mix Modes, at 491.52 MSPS, FS = 20 mA

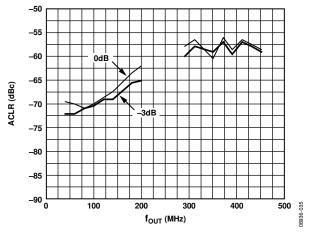


Figure 35. AD9783 ACLR for First Adjacent Channel Four-Carrier W-CDMA Over Digital Input Level Baseband and Mix Modes, at 491.52 MSPS, FS = 20 mA

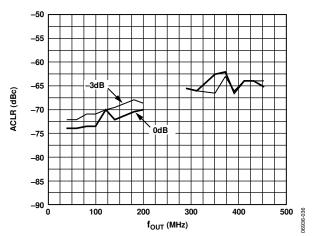


Figure 36. AD9783 ACLR for Second Adjacent Channel Four-Carrier W-CDMA Over Digital Input Level Baseband and Mix Modes, at 491.52 MSPS, FS = 20 mA

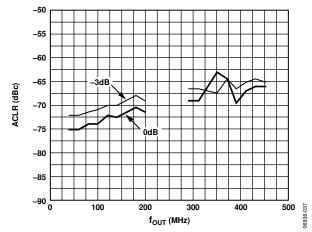


Figure 37. AD9783 ACLR for Third Adjacent Channel Four-Carrier W-CDMA Over Digital Input Level Baseband and Mix Modes, at 491.52 MSPS, FS = 20 mA

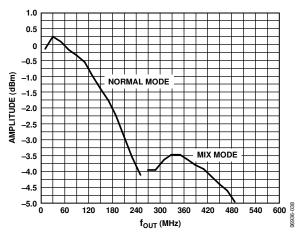


Figure 38. Nominal Power in the Fundamental, FS = 20 mA, at 500 MSPS, FS = 20 mA

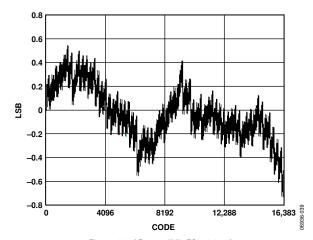


Figure 39. AD9781 INL, FS = 20 mA

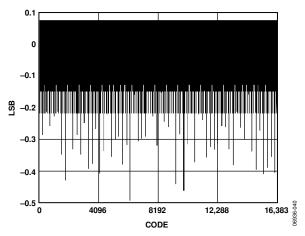


Figure 40. AD9781 DNL, FS = 20 mA

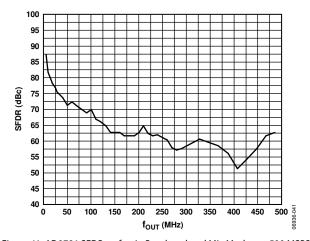


Figure 41. AD9781 SFDR vs. f_{OUT} in Baseband and Mix Modes, at 500 MSPS, FS=20~mA

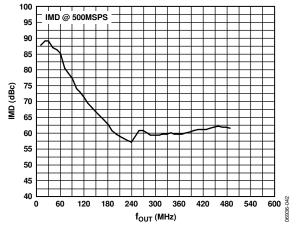


Figure 42. AD9781 IMD vs. $f_{\rm OUT}$ in Baseband and Mix Modes, at 500 MSPS, FS = 20 mA

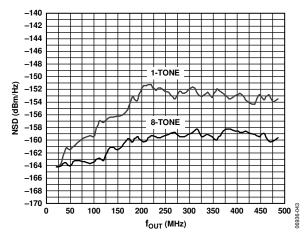


Figure 43. AD9781 One-Tone, Eight-Tone NSD vs. f_{OUT} in Baseband and Mix Modes, at 500 MSPS, FS = 20 mA

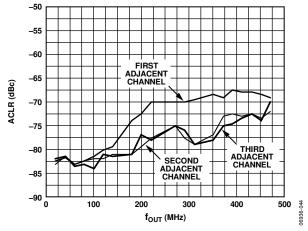


Figure 44. AD9781 ACLR for One-Carrier W-CDMA Baseband and Mix Modes, at 491.52 MSPS, FS = 20 mA

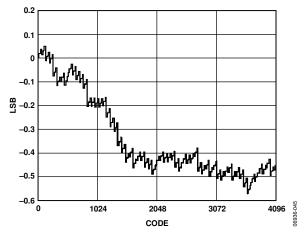


Figure 45. AD9780 INL, FS = 20 mA

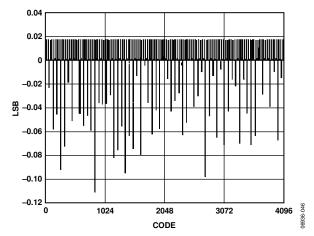


Figure 46. AD9780 DNL, FS = 20 mA

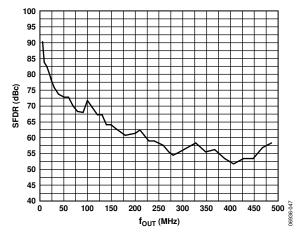


Figure 47. AD9780 SFDR vs. f_{OUT} in Baseband and Mix Modes, at 500 MSPS, FS = 20 mA

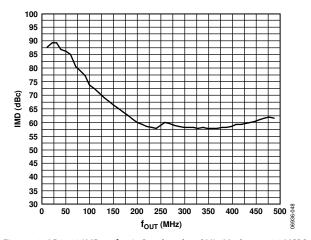


Figure 48. AD9780 IMD vs. f_{OUT} in Baseband and Mix Modes, at 500 MSPS, FS = 20 mA

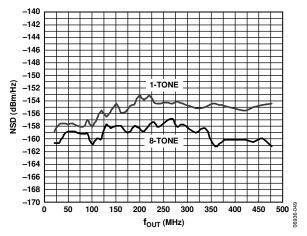


Figure 49. AD9780 One-Tone, Eight-Tone NSD vs. f_{OUT} in Baseband and Mix Modes, at 500 MSPS, FS = 20 mA

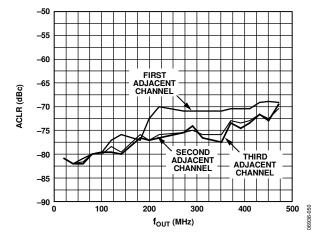


Figure 50. AD9780 ACLR for One-Carrier W-CDMA Baseband and Mix Modes, at 491.52 MSPS, FS = 20 mA

TERMINOLOGY

Linearity Error or Integral Nonlinearity (INL)

Linearity error is defined as the maximum deviation of the actual analog output from the ideal output, determined by a straight line drawn from zero scale to full scale.

Differential Nonlinearity (DNL)

DNL is the measure of the variation in analog value, normalized to full scale, associated with a 1 LSB change in digital input code.

Monotonicity

A DAC is monotonic if the output either increases or remains constant as the digital input increases.

Offset Error

Offset error is the deviation of the output current from the ideal of zero. For I_{OUTA} , 0 mA output is expected when the inputs are all 0s. For I_{OUTB} , 0 mA output is expected when all inputs are set to 1s.

Gain Error

Gain error is the difference between the actual and ideal output span. The actual span is determined by the difference between the output when all inputs are set to 1s and the output when all inputs are set to 0s.

Output Compliance Range

Output compliance range is the range of allowable voltage at the output of a current-output DAC. Operation beyond the maximum compliance limits can cause either output stage saturation or breakdown, resulting in nonlinear performance.

Temperature Drift

Temperature drift is specified as the maximum change from the ambient (25°C) value to the value at either $T_{\rm MIN}$ or $T_{\rm MAX}$. For offset and gain drift, the drift is reported in ppm of full-scale range (FSR) per degree Celsius. For reference drift, the drift is reported in ppm per degree Celsius.

Power Supply Rejection

Power supply rejection is the maximum change in the full-scale output as the supplies are varied from minimum to maximum specified voltages.

Settling Time

Settling time is the time required for the output to reach and remain within a specified error band around its final value, measured from the start of the output transition.

Spurious-Free Dynamic Range (SFDR)

SFDR is the difference, in decibels, between the peak amplitude of the output signal and the peak spurious signal between dc and the frequency equal to half the input data rate.

Total Harmonic Distortion (THD)

THD is the ratio of the rms sum of the first six harmonic components to the rms value of the measured fundamental. It is expressed as a percentage or in decibels.

Signal-to-Noise Ratio (SNR)

SNR is the ratio of the rms value of the measured output signal to the rms sum of all other spectral components below the Nyquist frequency, excluding the first six harmonics and dc. The value for SNR is expressed in decibels.

Adjacent Channel Leakage Ratio (ACLR)

ACLR is the ratio in dBc between the measured power within a channel relative to its adjacent channel.

Complex Image Rejection

In a traditional two-part upconversion, two images are created around the second IF frequency. These images usually waste transmitter power and system bandwidth. By placing the real part of a second complex modulator in series with the first complex modulator, either the upper or lower frequency image near the second IF can be rejected.

THEORY OF OPERATION

The AD9780/AD9781/AD9783 have a combination of features that make them very attractive for wired and wireless communications systems. The dual DAC architecture facilitates easy interface to common quadrature modulators when designing single sideband transmitters. In addition, the speed and performance of the devices allow wider bandwidths and more carriers to be synthesized than in previously available products.

All features and options are software programmable through the SPI port.

SERIAL PERIPHERAL INTERFACE

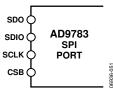


Figure 51. SPI Port

The serial peripheral interface (SPI) port is a flexible, synchronous serial communications port allowing easy interface to many industry-standard microcontrollers and microprocessors. The port is compatible with most synchronous transfer formats, including both the Motorola SPI and Intel® SSR protocols.

The interface allows read and write access to all registers that configure the AD9780/AD9781/AD9783. Single or multiple byte transfers are supported as well as MSB-first or LSB-first transfer formats. Serial data input/output can be accomplished through a single bidirectional pin (SDIO) or through two unidirectional pins (SDIO/SDO).

The serial port configuration is controlled by Register 0x00, Bits[7:6]. It is important to note that any change made to the serial port configuration occurs immediately upon writing to the last bit of this byte. Therefore, it is possible with a multibyte transfer to write to this register and change the configuration in the middle of a communication cycle. Care must be taken to compensate for the new configuration within the remaining bytes of the current communication cycle.

Use of a single-byte transfer when changing the serial port configuration is recommended to prevent unexpected device behavior.

GENERAL OPERATION OF THE SERIAL INTERFACE

There are two phases to any communication cycle with the AD9780/AD9781/AD9783: Phase 1 and Phase 2. Phase 1 is the instruction cycle, which writes an instruction byte into the device. This byte provides the serial port controller with information regarding Phase 2 of the communication cycle: the data transfer cycle.

The Phase 1 instruction byte defines whether the upcoming data transfer is a read or write, the number of bytes in the data transfer, and a reference register address for the first byte of the data transfer. A logic high on the CSB pin followed by a logic low resets the SPI port to its initial state and defines the start of the instruction cycle. From this point, the next eight rising SCLK edges define the eight bits of the instruction byte for the current communication cycle.

The remaining SCLK edges are for Phase 2 of the communication cycle, which is the data transfer between the serial port controller and the system controller. Phase 2 can be a transfer of one, two, three, or four data bytes as determined by the instruction byte. Using multibyte transfers is usually preferred, although single-byte data transfers are useful to reduce CPU overhead or when only a single register access is required.

All serial port data is transferred to and from the device in synchronization with the SCLK pin. Input data is always latched on the rising edge of SCLK, whereas output data is always valid after the falling edge of SCLK. Register contents change immediately upon writing to the last bit of each transfer byte.

Anytime synchronization is lost, the device has the ability to asynchronously terminate an I/O operation whenever the CSB pin is taken to logic high. Any unwritten register content data is lost if the I/O operation is aborted. Taking CSB low then resets the serial port controller and restarts the communication cycle.

INSTRUCTION BYTE

The instruction byte contains the information shown in Table 9.

Table 9.

MSB							LZR
B7	В6	B5	B4	В3	B2	B1	ВО
R/W	N1	N0	A4	А3	A2	A1	A0

Bit 7, R/W, determines whether a read or a write data transfer occurs after the instruction byte write. Logic 1 indicates a read operation. Logic 0 indicates a write operation.

Bits[6:5], N1 and N0, determine the number of bytes to be transferred during the data transfer cycle. The bits decode as shown in Table 10.

Table 10. Byte Transfer Count

N1	NO	Description			
0	0	Transfer one byte			
0	1	Transfer two bytes			
1	0	Transfer three bytes			
1	1	Transfer four bytes			

Bits[4:0], A4, A3, A2, A1, and A0, determine which register is accessed during the data transfer of the communication cycle. For multibyte transfers, this address is a starting or ending address depending on the current data transfer mode. For MSB-first format, the specified address is an ending address or the most significant address in the current cycle. Remaining register addresses for multiple byte data transfers are generated internally by the serial port controller by decrementing from the specified address. For LSB-first format, the specified address is a beginning address or the least significant address in the current cycle. Remaining register addresses for multiple byte data transfers are generated internally by the serial port controller by incrementing from the specified address.

MSB/LSB TRANSFERS

The serial port can support both MSB-first and LSB-first data formats. This functionality is controlled by Register 0x00, Bit 6. The default is Logic 0, which is MSB-first format.

When using MSB-first format (LSBFIRST = 0), the instruction and data bit must be written from MSB to LSB. Multibyte data transfers in MSB-first format start with an instruction byte that includes the register address of the most significant data byte. Subsequent data bytes are loaded into sequentially lower address locations. In MSB-first mode, the serial port internal address generator decrements for each byte of the multibyte data transfer.

When using LSB-first format (LSBFIRST = 1), the instruction and data bit must be written from LSB to MSB. Multibyte data transfers in LSB-first format start with an instruction byte that includes the register address of the least significant data byte. Subsequent data bytes are loaded into sequentially higher address locations. In LSB-first mode, the serial port internal address generator increments for each byte of the multibyte data transfer.

Use of a single-byte transfer when changing the serial port data format is recommended to prevent unexpected device behavior.

SERIAL INTERFACE PORT PIN DESCRIPTIONS Chip Select Bar (CSB)

Active low input starts and gates a communication cycle. It allows more than one device to be used on the same serial communication lines. CSB must stay low during the entire communication cycle. Incomplete data transfers are aborted anytime the CSB pin goes high. SDO and SDIO pins go to a high impedance state when this input is high.

Serial Clock (SCLK)

The serial clock pin is used to synchronize data to and from the device and to run the internal state machines. The maximum frequency of SCLK is 40 MHz. All data input is registered on the rising edge of SCLK. All data is driven out on the falling edge of SCLK.

Serial Port Data I/O (SDIO)

Data is always written into the device on this pin. However, SDIO can also function as a bidirectional data output line. The configuration of this pin is controlled by Register 0x00, Bit 7. The default is Logic 0, which configures the SDIO pin as unidirectional.

Serial Port Data Output (SDO)

Data is read from this pin for protocols that use separate lines for transmitting and receiving data. The configuration of this pin is controlled by Register 0x00, Bit 7. If this bit is set to a Logic 1, the SDO pin does not output data and is set to a high impedance state.

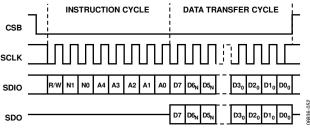


Figure 52. Serial Register Interface Timing Diagram, MSB First

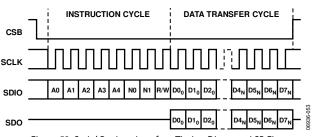


Figure 53. Serial Register Interface Timing Diagram, LSB First

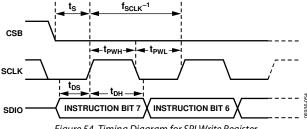


Figure 54. Timing Diagram for SPI Write Register

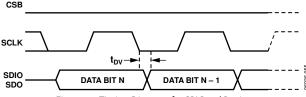


Figure 55. Timing Diagram for SPI Read Register

SPI REGISTER MAP

Table 11.

Register Name	Addr	Default	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SPI Control	0x00	0x00	SDIO_DIR	LSBFIRST	RESET					
Data Control	0x02	0x00	DATA			INVDCO				
Power-Down	0x03	0x00	PD_DCO	PD_INPT	PD_AUX2	PD_AUX1	PD_BIAS	PD_CLK	PD_DAC2	PD_DAC1
Setup and Hold	0x04	0x00	SET[3:0] H			HL	D[3:0]			
Timing Adjust	0x05	0x00	SAMP_DLY[4:0]							
Seek	0x06	0x00						LVDS low	LVDS high	SEEK
Mix Mode	0x0A	0x00					DAC1	MIX[1:0]	DAC2N	NIX[1:0]
DAC1 FSC	0x0B	0xF9	DAC1FSC[7:0]							
DAC1 FSC MSBs	0x0C	0x01							DAC1F	SC[9:8]
AUXDAC1	0x0D	0x00	AUXDAC1[7:0]							
AUXDAC1 MSB	0x0E	0x00	AUX1SGN	AUX1DIR					AUXDA	C1[9:8]
DAC2 FSC	0x0F	0xF9				DAC2F	SC[7:0]			
DAC2 FSC MSBs	0x10	0x01							DAC2F	SC[9:8]
AUXDAC2	0x11	0x00				AUXDA	C2[7:0]		•	
AUXDAC2 MSB	0x12	0x00	AUX2SGN	AUX2DIR					AUXDA	C2[9:8]
BIST Control	0x1A	0x00	BISTEN	BISTRD	BISTCLR					
BIST Result 1 Low	0x1B	0x00	BISTRES1[7:0]							
BIST Result 1 High	0x1C	0x00	BISTRES1[15:8]							
BIST Result 2 Low	0x1D	0x00	BISTRES2[7:0]							
BIST Result 2 High	0x1E	0x00	BISTRES2[15:8]							
Hardware Version	0x1F	N/A	VERSION[3:0] DEVICE[3:0]							

SPI REGISTER DESCRIPTIONS

Reading these registers returns previously written values for all defined register bits, unless otherwise noted.

Table 12.

Register	Address	Bit	Name	Function		
SPI Control	0x00	7	SDIO_DIR	0, operate SPI in 4-wire mode. The SDIO pin operates as an input only pin.		
				1, operate SPI in 3-wire mode. The SDIO pin operates as a bidirectional data line.		
		6	LSBFIRST	0, MSB first per SPI standard.		
				1, LSB first per SPI standard.		
				Only change LSB/MSB order in single-byte instructions to avoid erratic behavior due to bit order errors.		
		5	RESET	0, execute software reset of SPI and controllers, reload default register values except Register 0x00.		
				1, set software reset, write 0 on the next (or any following) cycle to release the reset		
Data Control	0x02	7	DATA	0, DAC input data is twos complement binary format.		
		1, DAC input data is unsi		1, DAC input data is unsigned binary format.		
		4	INVDCO	1, inverts the data clock output. Used for adjusting timing of input data.		
Power-Down	0x03	0x03 7 PD_DCO 1, power down data clock output driver circuit.		1, power down data clock output driver circuit.		
		6	PD_INPT	1, power down input.		
		5	PD_AUX2	1, power down AUX2 DAC		
		4	PD_AUX1	1, power down AUX1 DAC.		
		3	PD_BIAS	1, power down voltage reference bias circuit.		
		2	PD_CLK	1, power down DAC clock input circuit.		
		1	PD_DAC2	1, power down DAC2.		
		0	PD_DAC1	1, power down DAC1.		
Setup and Hold	0x04	7:4	SET[3:0]	4-bit value used to determine input data setup timing.		
·		3:0	HLD[3:0]	4-bit value used to determine input data hold timing.		
Timing Adjust	0x05	4:0	SAMP_DLY[4:0]	5-bit value used to optimally position input data relative to internal sampling clock.		
Seek	0x06	2	LVDS low	One of the LVDS inputs is above the input voltage limits of the IEEE reduced link specification.		
		1	LVDS high	One of the LVDS inputs is below the input voltage limits of the IEEE reduced link specification.		
		0	SEEK	Indicator bit used with LVDS_SET and LVDS HLD to determine input data timing margin.		
Mix Mode	0x0A	3:2	DAC1MIX[1:0]	00, selects normal mode, DAC1.		
				01, selects return-to-zero mode, DAC1.		
				10, selects return-to-zero mode, DAC1.		
				11, selects mix mode, DAC1.		
		1:0	DAC2MIX[1:0]	00, selects normal mode, DAC2.		
				01, selects return-to-zero mode, DAC2.		
				10, selects return-to-zero mode, DAC2.		
				11, selects mix mode, DAC2.		
DAC1 FSC	0x0B	7:0	DAC1FSC[9:0]	DAC1 full-scale 10-bit adjustment word.		
	0x0C	· ·		0x3FF, sets DAC full-scale output current to the maximum value of 31.66 mA.		
				0x200, sets DAC full-scale output current to the nominal value of 20.0 mA.		
				0x000, sets DAC full-scale output current to the minimum value of 8.66 mA.		

Register	Address	Bit	Name	Function	
AUXDAC1	0x0D	7:0	AUXDAC1[9:0]	AUXDAC1 output current adjustment word.	
	0x0E	1:0		0x3FF, sets AUXDAC1 output current to 2.0 mA.	
				0x200, sets AUXDAC1 output current to 1.0 mA.	
				0x000, sets AUXDAC1 output current to 0.0 mA.	
	0x0E	7 AUX1SGN 0, AUX1P output pin is active.		0, AUX1P output pin is active.	
				1, AUX1N output pin is active.	
		6	AUX1DIR	0, configures AUXDAC1 output to source current.	
				1, configures AUXDAC1 output to sink current.	
DAC2 FSC	0x0F	7:0	DAC2FSC[9:0]	DAC2 full-scale 10-bit adjustment word.	
	0x10	1:0		0x3FF, sets DAC full-scale output current to the maximum value of 31.66 mA.	
				0x200, sets DAC full-scale output current to the nominal value of 20.0 mA.	
				0x000, sets DAC full-scale output current to the minimum value of 8.66 mA.	
AUXDAC2	0x11	7:0	AUXDAC2[9:0]	AUXDAC2 output current adjustment word.	
	0x12	1:0 0x3FF, sets AUXDAC2 output current to 2.0 mA.		0x3FF, sets AUXDAC2 output current to 2.0 mA.	
				0x200, sets AUXDAC2 output current to 1.0 mA.	
				0x000, sets AUXDAC2 output current to 0.0 mA.	
	0x12	7	AUX2SGN	0, AUX2P output pin is active.	
				1, AUX2N output pin is active.	
		6	AUX2DIR	0, configures AUXDAC2 output to source current.	
				1, configures AUXDAC2 output to sink current.	
BIST Control	0x1A	7	BISTEN	1, enables and starts built-in self-test.	
		6	BISTRD	1, transfers BIST result registers to SPI for readback.	
		5	BISTCLR	1, reset BIST logic and clear BIST result registers.	
BIST Result 1	0x1B	7:0	BISTRES1[15:0]	16-bit result generated by BIST 1.	
	0x1C	7:0			
BIST Result 2	0x1D	7:0	BISTRES2[15:0]	16-bit result generated by BIST 2.	
	0x1E	7:0			
Hardware Version	0x1F	7:4	VERSION[3:0]	Read only register; indicates the version of the chip.	
		3:0	DEVICE[3:0]	Read only register; indicates the device type.	

SPI PORT, RESET, AND PIN MODE

In general, when the AD9780/AD9781/AD9783 are powered up, an active high pulse applied to the RESET pin should follow. This ensures the default state of all control register bits. In addition, once the RESET pin goes low, the SPI port can be activated; thus, CSB should be held high.

For applications without a controller, the AD9780/AD9781/ AD9783 also supports pin mode operation, which allows some functional options to be pin selected without the use of the SPI port. Pin mode is enabled anytime the RESET pin is held high.

In pin mode, the four SPI port pins take on secondary functions, as shown in Table 13.

Table 13. SPI Pin Functions (Pin Mode)

Pi Na	n ame	Pin Mode Function
SE	OIO	DATA (Register 0x02, Bit 7), bit value (1/0) equals pin state (high/low).
CS	SB	Enable mix mode. If CSB is high, Register 0x0A is set to 0x05, putting both DAC1 and DAC2 into mix mode.
SE	00	Enable full power-down. If SDO is high, Register 0x03 is set to 0xFF.

PARALLEL DATA PORT INTERFACE

The parallel port data interface consists of up to 18 differential signals, DCO, DCI, and up to 16 data lines (D[15:0]), as shown in Figure 56. DCO is the output clock generated by the AD9780/AD9781/AD9783 that is used to clock out the data from the digital data engine. The data lines transmit the multiplexed I and Q data words for the I and Q DACs, respectively. DCI provides timing information about the parallel data and signals the I/O status of the data.

As diagrammed in Figure 56, the incoming LVDS data is latched by an internally generated clock referred to as the data sampling signal (DSS). DSS is a delayed version of the main DAC clock signal, CLKP/CLKN. Optimal positioning of the rising and falling edges of DSS with respect to the incoming data signals results in the most robust transmission of the DAC data. Positioning the edges of DSS with respect to the data signals is achieved by selecting the value of a programmable delay element, SMP. A procedure for determining the optimal value of SMP is given in the Optimizing the Parallel Port Timing section.

In addition to properly positioning the DSS edges, maximizing the opening of the eye in the clock input (DCIP/DCIN) and data signals improves the reliability of the data port interface. The two sources of degradation that reduce the eye in the clock input and data signals are the jitter on these signals and the skew between them. Therefore, it is recommended that the clock input signals be generated in the same manner as the data signals with the same output driver and data line routing. In other words, it should be implemented as a 17^{th} data line with an alternating (010101 ...) bit sequence.

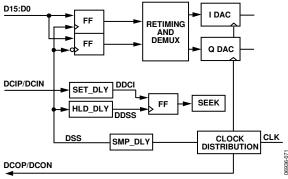


Figure 56. Digital Data Port Block Diagram

OPTIMIZING THE PARALLEL PORT TIMING

Before outlining the procedure for determining the delay for SMP (that is, the positioning of DSS with respect to the data signals), it is worthwhile to describe the simplified block diagram of the digital data port. As can be seen in Figure 57, the data signals are sampled on the rising and falling edges of DSS. From there, the data is demultiplexed and retimed before being sent to the DACs.

The clock input signal provides timing information about the parallel data, as well as indicating the destination (that is, I DAC or Q DAC) of the data. A delayed version of DCI is generated by a delay element, SET, and is referred to as DDCI. DDCI is sampled by a delayed version of the DSS signal, labeled as DDSS in Figure 56. DDSS is simply DSS delayed by a period of time, HLD. The pair of delays, SET and HLD, allows accurate timing information to be extracted from the clock input. Increasing the delay of the HLD block results in the clock input being sampled later in its cycle. Increasing the delay of the SET block results in the clock input being sampled earlier in its cycle. The result of this sampling is stored and can be queried by reading the SEEK bit. Because DSS and the clock input signal are the same frequency, the SEEK bit should be a constant value. By varying the SET and HLD delay blocks and seeing the effect on the SEEK bit, the setup-and-hold timing of DSS with respect to clock input (and, hence, data) can be measured.

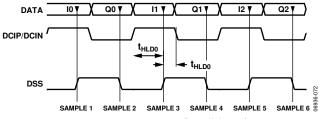


Figure 57. Timing Diagram of Parallel Interface

The incremental units of SET, HLD, and SMP are in units of real time, not fractions of a clock cycle. The nominal step size for SET and HLD is 80 ps. The nominal step size for SMP is 160 ps. Note that the value of SMP refers to Register 0x05, Bits[4:0], SET refers to Register 0x04, Bits[7:4], and HLD refers to Register 0x04, Bits[3:0].

A procedure for configuring the device to ensure valid sampling of the data signals follows. Generally speaking, the procedure begins by building an array of setup-and-hold values as the sample delay is swept through a range of values. Based on this information, a value of SMP is programmed to establish an optimal sampling point. This new sampling point is then double-checked to verify that it is optimally set.